



DATE: 22nd December, 2017

PCN #: 2308 (REV 2)

PCN Title: Additional FAB Source and Assembly/Test Site on Select Devices

Dear Customer:

This is an announcement of change(s) to products that are currently being offered by Diodes Incorporated.

We request that you acknowledge receipt of this notification within 30 days of the date of this PCN. If you require samples for evaluation purposes, please make a request within 30 days as well. Otherwise, samples may not be built prior to this change. Please refer to the implementation date of this change as it is stated in the attached PCN form. Please contact your local Diodes sales representative to acknowledge receipt of this PCN and for any sample requests.

The changes announced in this PCN will not be implemented earlier than 90 days from the notification date stated in the attached PCN form.

Previously agreed upon customer specific change process requirements or device specific requirements will be addressed separately.

For questions or clarification regarding this PCN, please contact your local Diodes sales representative.

Sincerely,

Diodes Incorporated PCN Team



PRODUCT CHANGE NOTICE

PCN-2308 REV 2

Notification Date:	Implementation Date:	Product Family:	Change Type:	PCN #:
22 nd December, 2017	22 nd March, 2018	Analog Semiconductors	Additional Fab and A/T Source	2308
TITLE				
Additional FAB Source (Chipbond LH), and Assembly/Test Site (SAT/Unisem) on Select Devices				
DESCRIPTION OF CHANGE				
This PCN is being issued to notify customers that in order to assure continuity of supply, Diodes has qualified an additional wafer Fab source for RDL process (Chipbond KF) located in Hsinchu, Taiwan as well as additional assembly/test sites Diodes Incorporated / Shanghai, China (SAT), and (Unisem) located in Chengdu, China on selected devices. Full electrical characterization and high reliability testing has been completed on representative part numbers to ensure there is no change to device functionality or electrical specifications in the datasheet. See attached qualification report.				
REV 2: Correction of name and location of additional Chipbond wafer Fab from 'LH' to 'KF'				
IMPACT				
Continuity of Supply. No change in product performance.				
PRODUCTS AFFECTED				
Table 1 - Qualify Additional A/T Source (SAT) Diodes Incorporated / Shanghai, China with Au to Cu wire and BOM Table 2 -Qualify Additional FAB Source for RDL (Chipbond KF Hsinchu, Taiwan) Table 3 - Qualify Additional A/T Source (Unisem) located in Chengdu, China with POD delta, and pin 1 marking identifier				
WEB LINKS				
Manufacturer's Notice:	https://www.diodes.com/quality/product-change-notices/diodes-product-change-notices/			
For More Information Contact:	http://www.diodes.com/contacts			
Data Sheet:	http://www.diodes.com/products			
DISCLAIMER				
Unless a Diodes Incorporated Sales representative is contacted in writing within 30 days of the posting of this notice, all changes described in this announcement are considered approved.				

Table 1 - Qualify Additional A/T Source (SAT) Diodes Incorporated / Shanghai, China with Au to Cu wire and BOM

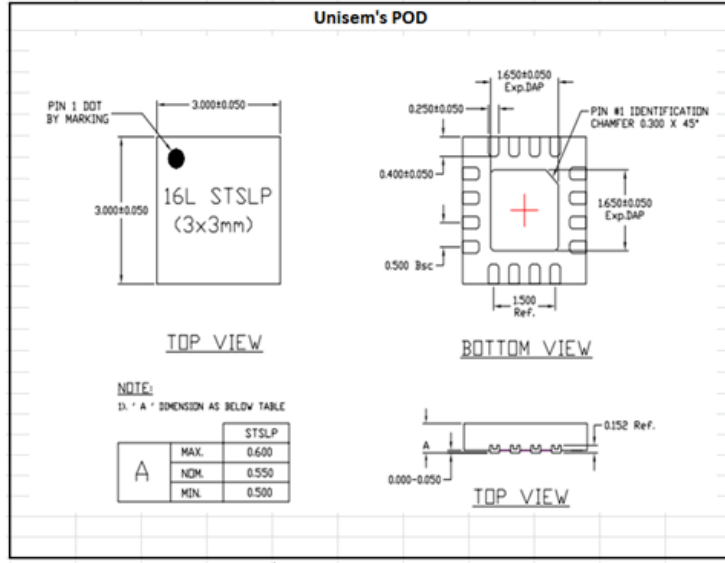
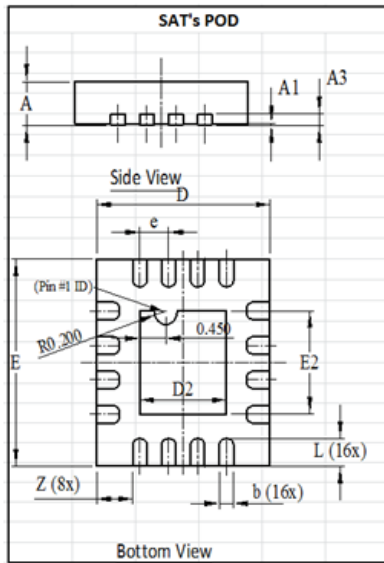
AP2112R5-1.2TRG1	AP2112R5-1.8TRG1	AP2112R5-2.5TRG1	AP2112R5-2.6TRG1	AP2112R5-3.3TRG1	AP2112R5A-1.2TRG1
AP2112R5A-1.8TRG1	AP2112R5A-2.5TRG1	AP2112R5A-2.6TRG1	AP2112R5A-3.3TRG1	AP2115R5-1.2TRG1	AP2115R5-1.8TRG1
AP2115R5-2.5TRG1	AP2115R5-3.3TRG1	AP2115R5A-1.2TRG1	AP2115R5A-1.8TRG1	AP2115R5A-2.5TRG1	AP2115R5A-3.3TRG1

Table 2 -Qualify Additional FAB Source for RDL (Chipbond **KF) Hsinchu, Taiwan**

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Table 3 - Qualify Additional A/T Source (Unisem) located in Chengdu, China with POD delta and pin 1 marking identifier

PAM8904JER					
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POD compare				
U-QFN3030-16 in DS				
SAT				Unisem
Dim	Min	Max	Typ	
A	0.55	0.65	0.6	0.55±0.05
A1	0	0.05	0.02	max0.05
A3	—	—	0.15	max0.15
b	0.18	0.28	0.23	0.25±0.05
D	2.95	3.05	3	3±0.05
D2	1.4	1.6	1.5	1.65±0.05
E	2.95	3.05	3	3±0.05
E2	1.4	1.6	1.5	1.5
e	—	—	0.5	0.5
L	0.35	0.45	0.4	0.4±0.05
Z	—	—	0.625	0.625
All Dimensions in mm				